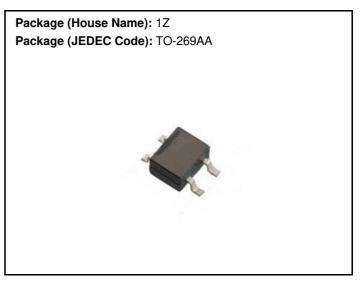
S1ZAS4

Schottky Barrier Diodes 40V, 1.2A

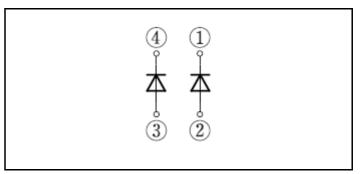
Feature

- SMD
- $\bullet \ Low \ V_F$
- Pb free terminal
- RoHS:Yes

OUTLINE



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : TI=25°C)

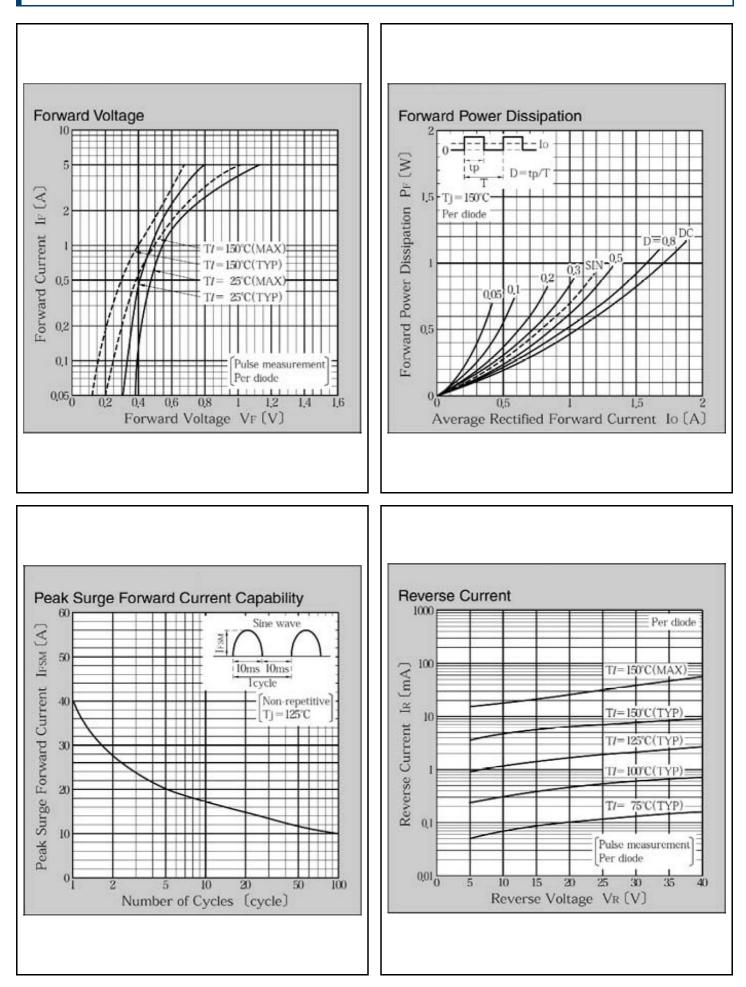
Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-40 to 150	°C
Junction temperature	Tj		150	°C
Repetitive peak reverse voltage	V _{RRM}		40	V
Repetitive peak surge reverse voltage	V _{RRSM}	Pulse width 0.5ms, duty=1/40	45	V
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On alumina substrate, 1 element operation, Ta=49°C	1.2	A
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On alumina substrate, 2 elements operation, Ta=45°C, per diode	0.9	A
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, 1 element operation, Ta=47°C	1	А
Average forward current	I _F (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, 2 elements operation, Ta=43°C	0.72	А
Surge forward current	I _{FSM}	50Hz sine wave, Non-repetitive, 1cycle, Peak value, Tj=125°C	40	А
Repetitive peak surge reverse power	P _{RRSM}	Pulse width 10µs, Tj=25°C, per diode	60	W

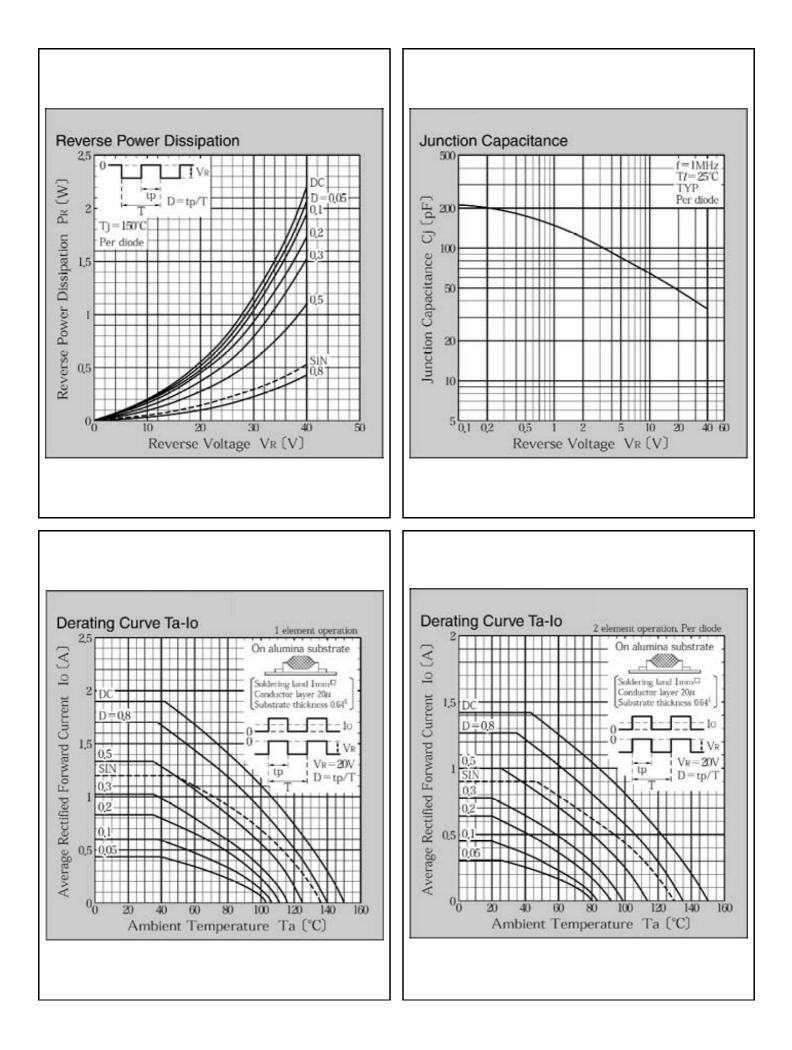
* : See the original Specifications

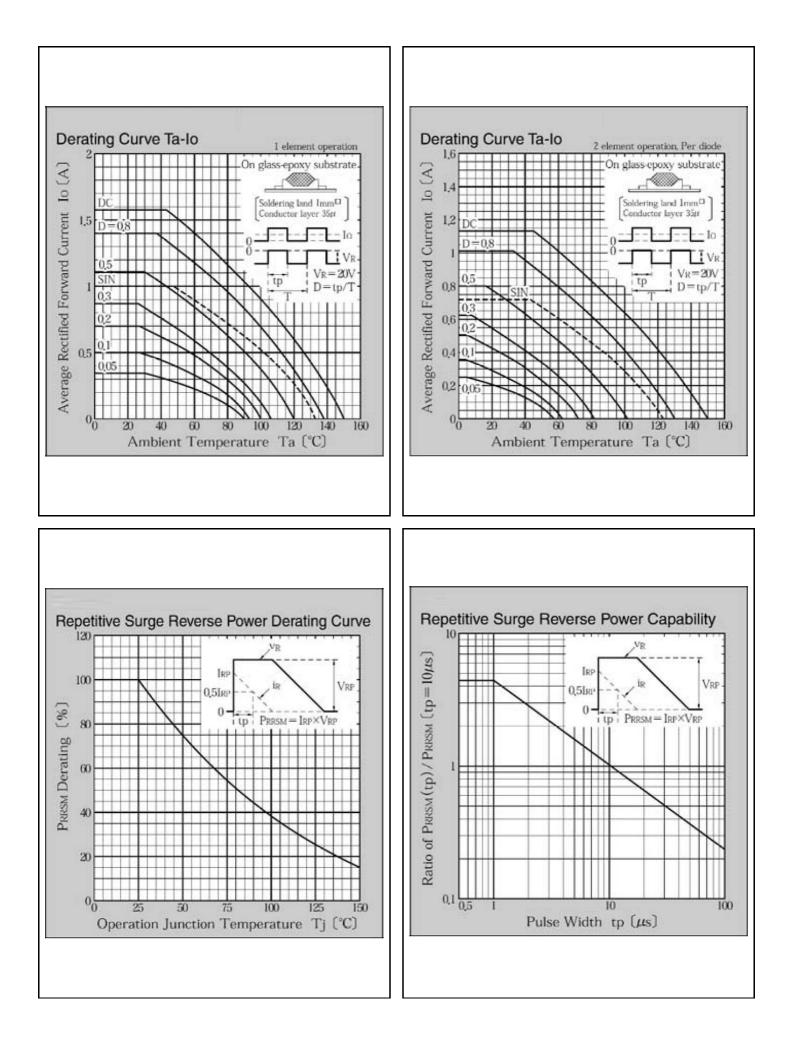
Electrical Characteristics (unless otherwise specified : TI=25°C)								
Item	Symbol	Conditions	Ratings			Unit		
	Cymbol		MIN	ТҮР	MAX	onit		
Forward voltage	V _F	IF=1A, Pulse measurement, per diode			0.55	V		
Reverse current	I _R	VR=40V, Pulse measurement, per diode			1	mA		
Total capacitance	Ct	f=1MHz, VR=10V, per diode		65		pF		
Thermal resistance	Rth(j-l)	Junction to lead			25	°C/W		
Thermal resistance	Rth(j-a)	Junction to ambient, On alumina substrate, 1 element operation			93	°C/W		
Thermal resistance	Rth(j-a)	Junction to ambient, On alumina substrate, 2 elements operation, per diode			140	°C/W		
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate, 1 element operation			120	°C/W		
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate, 2 elements operation, per diode			186	°C/W		

* : See the original Specifications

CHARACTERISTIC DIAGRAMS

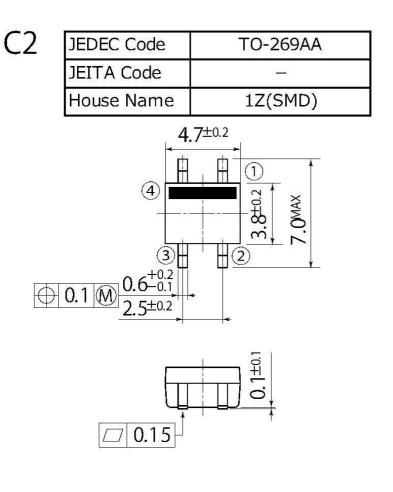


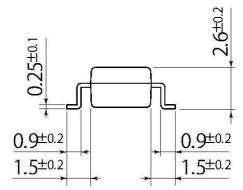


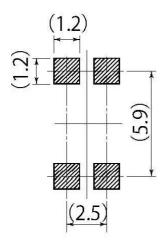


unit:mm

scale: 4/1







Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

Notes

- 1. If you wish to use any such product, please be sure to refer to the specifications issued by Shindengen.
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[Special applications]

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